## nexperia

## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier Nexperia B.V.		User Part Number BAT854CW-Q										
								Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		Part Description       Nexperia DHAM     Schottky       SMD package     SMD package		
Test Conditions	Duration	# Lots	# Quantity	# Rejects								
	TEST				<b>.</b> ,							
	Pre- and Post-Stress											
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
		JESD22-A113			· ·							
		Bake Tamb = 125 °C	24 hours									
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours									
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0						
		MIL-STD-750-1										
	HTRB	M1038 Method A										
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet										
# B1	Bias	reverse voltage <sup>[1]</sup>	1000 hours	206	9320	0						
	тс	JESD22-A104										
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0						
	UHAST	JESD22-A118										
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %	96 hours	311	14080	0						
		JESD22-A102	50 110013	511	14000	0						
	AC	Tamb = 121 °C, RH = 100 %										
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)										
	H3TRB	JESD22-A101										
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1], [2]</sup>	1000 hours	311	14080	0						
		MIL-STD-750 Method 1037										
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =										
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	312	14120	0						
	RSH	JESD22-A111										
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	269	8070	0						
	SD											
# C10	Solderability	J-STD-002		222	6660	0						

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

confidence level of <i>n</i> , defated to 55°C, activation energy 0.7 eV, test time 100 to 1000 hours	nce level 60%, derated to 55 °C, activation energy 0.7 eV, t	test time 168 to 1000 nours
---	--	-----------------------------

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com